

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

**CONVEYING PARTY DATA**

Name	Execution Date
Mitsuo SEKINE	10/08/2008
Takeshi YAMADA	11/05/2008
Hisao SANEYOSHI	11/10/2008
Kohji SEIO	10/08/2008

**RECEIVING PARTY DATA**

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State/Country:	JAPAN
Postal Code:	152-8550

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Street Address:	1-6-1, Ohtemachi, Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	100-8185

**PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	12224677

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3749-0127PUS1

NAME OF SUBMITTER:

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Total Attachments: 2

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# BIRCH, STEWART, KOLASCH & BIRCH, LLP

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UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

## ASSIGNMENT

Application No. 12/224,677 Filed March 8, 2007

**Insert Name(s) of Inventor(s)** **\*\*\* (Given Name FAMILY NAME (ALL CAPS)) \*\*\***

WHEREAS, Mitsuo SEKINE; Takeshi YAMADA; Hisao SANEYOSHI; and Kohji SEIO (hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in:

**Insert Title of Invention** 2'-HYDROXYL GROUP-MODIFIED RIBONUCLEOSIDE DERIVATIVES

for which an application for Letters Patent of the United States of America has been executed by the undersigned (except in the case of a provisional application)

**Insert Date of Signing of Application** on Oct. 8, 2008; Nov. 5, 2008; Nov. 10, 2008; and

**Insert Name of Assignee** WHEREAS, **TOKYO INSTITUTE OF TECHNOLOGY; and Kyowa Hakko Kirin Co., Ltd.**  
**Insert Address of Assignee** of 2-12-1, Ookayama, Meguro-ku, Tokyo 1528550 Japan; and 1-6-1, Ohtemachi, Chiyoda-ku, Tokyo 1008185 Japan, respectively

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and

**CHECK BOX IF APPROPRIATE**  **in any foreign countries.**

NOW, THEREFORE, in consideration of the sum of Ten Dollars (\$10.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents does sell, assign and transfer unto said Assignees the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries;

and to any and all divisions, reissues, continuations, conversions and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignees may deem necessary or expedient.

The undersigned agree (s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignees in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.


The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignees and to vest all rights therein hereby conveyed to said Assignees as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

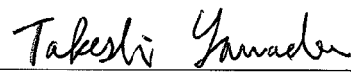
The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignees, as Assignees of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

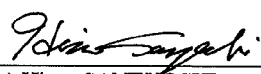
The undersigned hereby grant(s) the law firm of Birch, Stewart, Kolasch & Birch, LLP the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

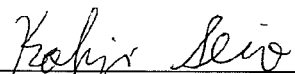
The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date Oct. 8, 2008, Name of Inventor   
(signature) Mitsuo SEKINE

Date 11/5/2008, Name of Inventor   
(signature) Takeshi YAMADA

Date Nov. 10, 2008, Name of Inventor   
(signature) Hisao SANEYOSHI

Date Dec. 8, 2008, Name of Inventor   
(signature) Kohji SEIO

Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_  
(signature)